

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5393968

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIN GYU SUNG	11/14/2018
JAE YOUNG LEE	11/26/2018
JOHANNES VAN MEER	02/22/2019
SONY VARGHESE	11/15/2018
NAUSHAD K. VARIAM	02/01/2019
RECEIVING PARTY DATA	
Name:	APPLIED MATERIALS, INC.
Street Address:	3050 BOWERS AVENUE
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16186004
CORRESPONDENCE DATA	
Fax Number:	(919)999-2798
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	919-636-4767
Email:	bjackson@kdbfirm.com
Correspondent Name:	KACVINSKY DAISAK BLUNI PLLC
Address Line 1:	101 CARNEGIE CENTER SUITE 106
Address Line 4:	PRINCETON, NEW JERSEY 08540
ATTORNEY DOCKET NUMBER:	44015600-2
NAME OF SUBMITTER:	BARBARA J. JACKSON
SIGNATURE:	/Barbara J. Jackson/
DATE SIGNED:	02/26/2019
Total Attachments: 9	
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ASSIGNMENT

WHEREAS, the undersigned, to wit:

Min Gyu Sung
Jae Young Lee
Johannes Van Meer
Sony Varghese
Naushad K. Variam

(Hereinafter collectively ASSIGNOR), have/has made a certain new and useful invention as set forth in an application for United States Letters Patent, entitled:

FIN DAMAGE REDUCTION DURING PUNCH THROUGH IMPLANTATION OF FINFET DEVICE

(X only one):

- (A) which was executed concurrently herewith and is being filed herewith in the United States Patent and Trademark Office;
- (B) which was executed on _____, 20____, and is being filed herewith in the United States Patent and Trademark Office;
- (C) which was filed as US Patent Application No. 16/186,004, filed on November 9, 2018

AND WHEREAS, Applied Materials, Inc., (hereinafter ASSIGNEE), a corporation organized and existing under the laws of the state of Delaware, and having its principal place of business at 3050 Bowers Avenue, Santa Clara, California, 95054, is desirous of acquiring the entire right, title, and interest in and to said invention and any and all patents that may be obtained therefore, and in and to said application and any and all patents that may issue therefrom;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR does hereby sell, assign, transfer, and set over unto said ASSIGNEE, its successors, assigns, and legal representatives, all right, title, and interest in and to said invention throughout the world, and any and all patents of the United States and foreign countries that may be obtained therefor, and in and to said application, including any and all continuations, continuations-in-part, divisionals, reissues, re-examinations, substitutions, and extensions thereof, and any and all patents of the United States and foreign countries that may issue therefrom, such right, title, and interest including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in the name of said ASSIGNEE, its successors, assigns, and legal representatives throughout the world, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, and all rights to register said invention in appropriate registries;

ASSIGNOR also does hereby covenant that it has the full right to convey the entire right, title, and interest herein assigned, and that it has not and will not execute any agreement in conflict herewith;

ASSIGNOR also does hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all Letters Patent of the United States on said invention or resulting from said application, including any continuations, continuations-in-part, divisions, reissues, re-examinations, substitutions, and extensions thereof, to said ASSIGNEE, its successors, assigns, and legal representatives as the ASSIGNEE of the entire right, title, and interest herein assigned;

ASSIGNOR also does hereby agree to, at any time, upon request, without further or additional consideration, but at the expense of said ASSIGNEE, its successors, assigns, or legal representatives, execute and deliver any and all papers, make all rightful oaths, and do all lawful acts that may be necessary or desirable to perfect the entire right, title, and interest here assigned in said ASSIGNEE, its successors, assigns, and legal representatives, and generally do everything possible to vest the entire right, title and interest herein assigned in said ASSIGNEE, its successors, assigns, and legal representatives;

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ASSIGNOR also does hereby agree to, at any time, upon request, without further or additional consideration but at the expense of said ASSIGNEE, its successors, assigns, and legal representatives, communicate to said ASSIGNEE, its successors, assigns, and legal representatives, any known facts relating to said invention or said application or any patent issuing therefor or therefrom, and testify as to the same in any interference or other litigation proceeding when requested to do so, and aid said ASSIGNEE, its successors, assigns, and legal representatives, in obtaining and enforcing property protection for said invention in all countries;

ASSIGNOR also does hereby grant the Legal Department of Varian Semiconductor Equipment Associates, Inc., at the address shown above, the power to insert on this assignment any further information, including, but not limited to application number(s) and filing date(s), which may be necessary or desirable in order to comply with any rule or request of the United States Patent and Trademark Office for the purposes of recording this document.

ASSIGNOR also does now hereby execute this document on the date(s) indicated below:

11/14/2018
Date

Min Gyu Sung
Name: Min Gyu Sung

Date

Name: Jae Young Lee

2-27-2011
Date


Name: Johannes Van Meer

Date

Name: Sony Varghese

Date

Name: Naushad K. Variam

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ASSIGNOR also does now hereby execute this document on the date(s) indicated below:

Date

11/26/18

Date

Name: Min Gyu Sung

Name: Jae Young Lee

Date

11/15/18

Date

Name: Johannes Van Meer



Name: Somy Varghese

Date

Name: Naushad K. Variam

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Name: Naushad K. Variam